L	Hits	Search Text	DB	Time stamp
Number				
1	21125	(smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27 10:27
2	3248	(least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27
3	361	((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)) )) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27
4	742	((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)) )) and (resin encapsulant epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27
5	576		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27
6	105	(bump ball flip flipchip) and ((((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)) )) and (resin encapsulant epoxy)) not (((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)) )) and package))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27
7	2241072	(flipchip flip die chip dice ic semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/27 09:53
8	403564	<pre>(least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit)) )</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 09:56
9	38492	(bump ball flip flipchip) same ((least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27 10:31
10	2438	<pre>((bump ball flip flipchip) same ((least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit)) ))) same (resin encapsulant epoxy)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27 10:30
11	15795	(smooth blunt curved abrupt frank dull) with (die chip dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27

				2002/07/27
12	62	<pre>((smooth blunt curved abrupt frank dull) with (die chip dice ic (integrated adj circuit)) ) and (((bump ball flip</pre>	USPAT; US-PGPUB; EPO; JPO;	2002/07/27 10:01
ļ		flipchip) same ((least stacked multi	DERWENT;	
		multiple plurality) same ((flipchip flip	IBM_TDB	
		<pre>die chip dice ic semiconductor  (integrated adj circuit)) ))) same (resin</pre>		
		encapsulant epoxy))		
13	60	(((smooth blunt curved abrupt frank dull)	USPAT;	2002/07/27
		with (die chip dice ic (integrated adj	US-PGPUB;	10:26
		<pre>circuit)) ) and (((bump ball flip flipchip) same ((least stacked multi</pre>	EPO; JPO; DERWENT;	
		multiple plurality) same ((flipchip flip	IBM TDB	
		die chip dice ic semiconductor	_	
		(integrated adj circuit))))) same (resin		
]		<pre>encapsulant epoxy))) not ((bump ball flip flipchip) and ((((least stacked multi</pre>		
		multiple plurality) same ((smooth blunt		
		curved abrupt frank dull) with (die chip		
		dice ic semiconductor (integrated adj		
		circuit)) )) and (resin encapsulant epoxy)) not (((least stacked multi	:	
		multiple plurality) same ((smooth blunt		
		curved abrupt frank dull) with (die chip		
		dice ic semiconductor (integrated adj		
14	2534	circuit)) )) and package))) 257/723	USPAT;	2002/07/27
* *	2001		US-PGPUB;	10:26
			EPO; JPO;	
			DERWENT; IBM TDB	
15	1609	257/686	USPAT;	2002/07/27
			US-PGPUB;	10:26
	}		EPO; JPO;	
			DERWENT; IBM TDB	
16	751	257/685	USPAT;	2002/07/27
			US-PGPUB;	10:26
			EPO; JPO; DERWENT;	
			IBM_TDB	
17	1434	257/777	USPAT;	2002/07/27
			US-PGPUB; EPO; JPO;	10:26
	1		DERWENT;	
			IBM_TDB	
18	2360	257/778	USPĀT; US-PGPUB;	2002/07/27
			EPO; JPO;	10.20
			DERWENT;	
		ATT (722	IBM_TDB	2002/07/27
19	1583	257/738	USPAT; US-PGPUB;	2002/07/27
			EPO; JPO;	
			DERWENT;	
	1050	0.7.7.72	IBM_TDB USPAT;	2002/07/27
20	1970	257/737	USPAT; US-PGPUB;	10:26
			EPO; JPO;	
			DERWENT;	
21	7001	257/722 257/696 257/605 257/777 257/770	IBM_TDB USPAT;	2002/07/27
21	7081	257/723 257/686 257/685 257/777 257/778 257/738 257/737	US-PGPUB;	10:27
			EPO; JPO;	
			DERWENT;	
22	111413	(smooth blunt curved abrupt frank dull	IBM_TDB USPAT;	2002/07/27
22	111413	shape irregular) with (die chip dice ic	US-PGPUB;	10:29
		semiconductor (integrated adj circuit))	EPO; JPO;	
1			DERWENT;	
			IBM_TDB	l

	1000	//	IICDAE :	2002/07/27
23	1552	((smooth blunt curved abrupt frank dull shape irregular) with (die chip dice ic	USPAT;	2002/07/27
	ľ	snape irregular) with (die Chip dice ic   semiconductor (integrated adj circuit)) )	US-PGPUB;	10:29
		and (257/723 257/686 257/685 257/777	EPO; JPO; DERWENT;	
1		257/778 257/738 257/737)	IBM TDB	
24	90288	((smooth blunt curved abrupt frank dull	USPAT;	2002/07/27
24	90200	shape irregular) with (die chip dice ic	US-PGPUB;	10:29
İ		semiconductor (integrated adj circuit)) )	EPO; JPO;	10.29
		not ((smooth blunt curved abrupt frank	DERWENT;	
1		dull) with (die chip dice ic	IBM TDB	
		semiconductor (integrated adj circuit)) )	1011_100	
25	1359		USPAT;	2002/07/27
23	1333	shape irregular) with (die chip dice ic	US-PGPUB;	10:29
		semiconductor (integrated adj circuit)))	EPO; JPO;	10.25
1		not ((smooth blunt curved abrupt frank	DERWENT;	
ļ		dull) with (die chip dice ic	IBM TDB	
1		semiconductor (integrated adj circuit))		
		)) and (257/723 257/686 257/685 257/777		
]		257/778 257/738 257/737)		
26	1299		USPAT;	2002/07/27
		and ((((smooth blunt curved abrupt frank	US-PGPUB;	10:30
		dull shape irregular) with (die chip dice	EPO; JPO;	
		ic semiconductor (integrated adj	DERWENT;	:
ļ		circuit)) ) not ((smooth blunt curved	IBM TDB	
		abrupt frank dull) with (die chip dice ic	·	
		semiconductor (integrated adj circuit))		
		)) and (257/723 257/686 257/685 257/777		ł
		257/778 257/738 257/737))		
27	983	((least stacked multi multiple plurality)	USPAT;	2002/07/27
		and ((((smooth blunt curved abrupt frank	US-PGPUB;	10:31
		dull shape irregular) with (die chip dice	EPO; JPO;	
		ic semiconductor (integrated adj	DERWENT;	
}		circuit)) ) not ((smooth blunt curved	IBM_TDB	
		abrupt frank dull) with (die chip dice ic	_	
1		semiconductor (integrated adj circuit))		
	1	)) and (257/723 257/686 257/685 257/777		
		257/778 257/738 257/737))) and (resin		
1		encapsulant epoxy)		
28	755	(bump ball flip flipchip) and (((least	USPAT;	2002/07/27
		stacked multi multiple plurality) and	US-PGPUB;	10:32
		((((smooth blunt curved abrupt frank dull	EPO; JPO;	
	1	shape irregular) with (die chip dice ic	DERWENT;	
-		semiconductor (integrated adj circuit)) )	IBM_TDB	
		not ((smooth blunt curved abrupt frank		
}		dull) with (die chip dice ic		
		semiconductor (integrated adj circuit))		
1		)) and (257/723 257/686 257/685 257/777		
		257/778 257/738 257/737))) and (resin		
		encapsulant epoxy))		